# **Specifications**

Drawing No.	UKY1C-H1-14D83-00[43] 1/11
Issued Date.	Dec,12,2014

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# TO: KED USA

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Quartz Crystal
Product Model	CX3225SB
Frequency	54000kHz
Customer Part Number	-
Customer Specification Number	-
KYOCERA Part Number	CX3225SB54000D0WPSC2
Remarks Pb-Free, RoHS Com	bliant, MSL 1

## Customer Acceptance

Accept Signature	Approved Date	
	Department	
	Person in charge	

# Seller KYOCERA Crystal Device Corporation (Sales Division) 6 Takeda Tobadono-cho, Fushimi-ku, Kyoto 612-8501 Japan TEL. No. 075-604-3500 FAX. No. 075-604-3501

# Manufacturer

Crystal Units Division 5850, Higashine-Koh, Higashine-Shi, Yamagata 999-3701 Japan TEL. No. 0237-43-5611 FAX. No. 0237-43-5615

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Crystal Device Corporation Crystal Units Engineering Section 1 Crystal Units Division	T. Noritake	K. Yamazaki	T. Nitoube	Y. Kikuchi

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# **Revision History**

Rev.No.	Description of revise	Date	Approved by	Checked by	Issued by
1	First Edition	Dec,12,2014	K. Yamazaki	T. Nitoube	Y. Kikuchi

# **1. APPLICATION**

This specification sheet is applied to quartz crystal "CX3225SB54000D0WPSC2"

# 2. KYOCERA PART NUMBER

CX3225SB54000D0WPSC2

# 3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature	Topr	-40 to +85	С°	
Storage Temperature range	Tstg	-40 to +85	C°	

# 4. CHARACTERISTICS

# **ELECTRICAL CHARACTERISTICS**

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration			Fundamental				
Nominal Frequency	F0		54		MHz		
Nominal Temperature	T <sub>NOM</sub>		+25		°C		
Load Capacitance	CL		8.0		pF		
Frequency Stability & Accuracy	df/F	-50.0		+50.0	PPM	*Note	Initial:±15ppm TC:±30ppm
Activity Dip		-2.0		+2.0	ppm/°C	-40 to +85°C	
Equivalent Series Resistance	ESR			23	Ω		
Shunt Capacitance	C0			2.0	pF		
Pull ability			31.0		ppm/pF		
Drive Level	Pd	0.01		200	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

\*Note : The sum of Frequency stability and accuracy is guaranteed with the following conditions

1) Temperature range of -40°C to +85°C

2) Frequency drift after 2 solder reflows

3) Drive power from 25  $\mu A$  to 200  $\mu A$ 

4) 15 years of aging at any temperature from -40°C to +85°C

# 5. Measurement Condition

Drive Level

5.1 Frequency measurement

Measuring instrument :	IEC PI-Network Test Fixture
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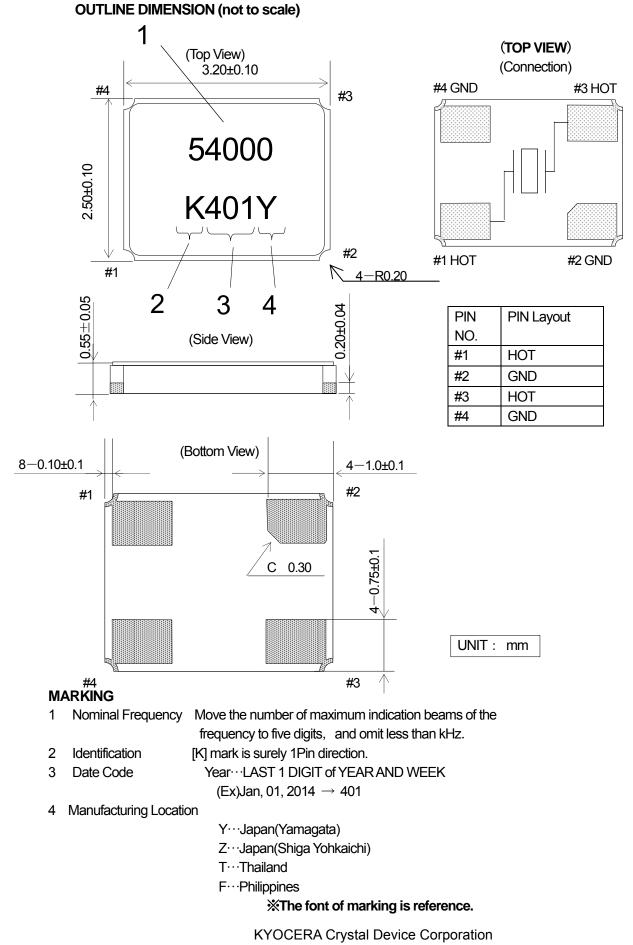
- Load Capacitance
  - : 8.0pF : 10µW

# 5.2 Equivalent series resistance (ESR) measurement

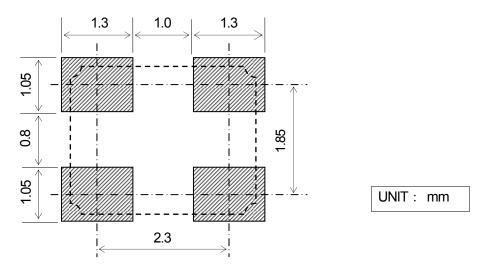
Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Ser

- Drive Level
- : Series : 10µW

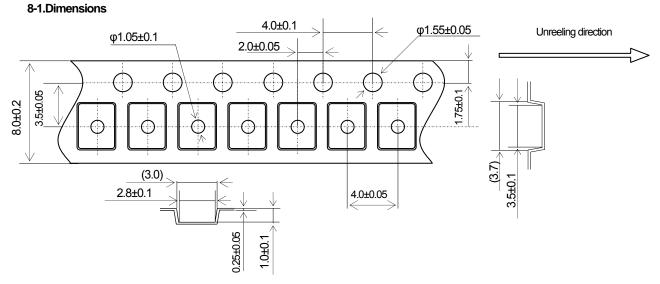


# 6. APPEARANCES, PHYSICAL DIMENSION

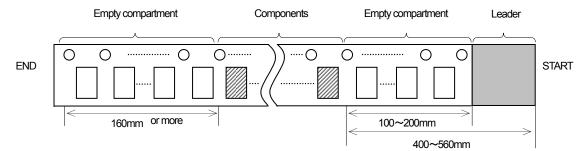


# 7. RECOMMENDED LAND PATTERN (not to scale)

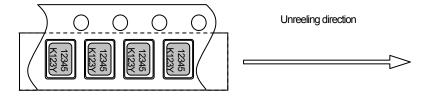
# 8.TAPING & REEL



#### 8-2.Leader and trailer tape



#### 8-3.Direction (The direction shall be seen from the top cover tape side)



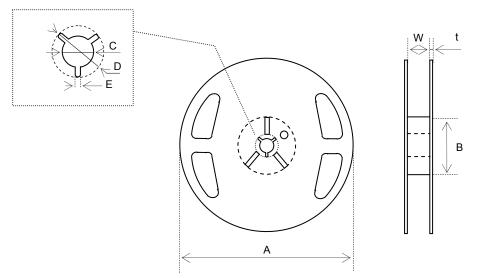
#### 8-4.Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 8-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.

165°~180° Cover tap Career tape

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## 8-5.Reel Specification



# In the case of Φ180 Reel (3,000 pcs max, every 1,000 pcs)

		, · · · <b>,</b> , · · · <b>,</b>		
Symbol	А	В	С	D
Dimension	φ <b>180 +0/-3</b>	φ <b>60 +1/-0</b>	φ <b>13±0.2</b>	φ <b>21±0.8</b>
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit:mm)

# In the case of Φ330 Reel (10,000 pcs max, every 1,000 pcs)

		<u> </u>		
Symbol	А	В	С	D
Dimension	φ <b>330±2.0</b>	φ <b>100±1.0</b>	φ <b>13±0.2</b>	φ <b>21±0.8</b>
Symbol	E	W	t	
Dimension	2.0±0.5	9.5±0.5	2.2±0.1	

(Unit:mm)

9. Environmental requirements After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$ And CI, $\pm 20\%$ or 5 $\Omega$ of large value.					
9.1 Resistance to Shock	Test condition Natural dropped from height 100cm onto hard wood board in 3 times				
9.2 Resistance to Vibration	Test conditionfrequency: 10 - 55 - 10 HzAmplitude: 1.5mmCycle time: 15 minutesDirection: X,Y,Z (3direction),2 h each.				
9.3 Resistance to Heat	Test condition The quartz crystal unit shall be stored at a temperature of +85±2°C for 500 h. Then it shal be subjected to standard atmospheric conditions for 1 h ,after whichi measurement shall be made.				
9.4 Resistance to Cold	Test condition The quartz crystal unit shall be stored at a temperature of -40±2°C for 500 h. Then it shal be subjected to standard atmospheric conditions for 1 h ,after whichi measurement shall be made.				
9.5 Thermal Shock	Test condition The quartz crystal unit shall be subjected to 500 succesive change of temperature cycles , each as shown in table below, Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made. Cycle $:-40\pm2^{\circ}$ C (30min.) to $+25\pm2^{\circ}$ C (5min.) to $+85\pm2^{\circ}$ C (30min.) to $+25\pm2^{\circ}$ C (5min.)				

9.6 Resistance to Moisture	Test condition The quartz crystal unit shall be stored at a temperature of +60±2°C wich relative humidity of 90% to 95% for 240 h. Then it shall be subjected to standard atmospheric conditions for 1h, after which measurements shall be made

9.7 Soldering condition

1.) Material of solder

Kind … lead free solder paste

Melting point ··· +220±5°C

2.) Reflow temp.profile

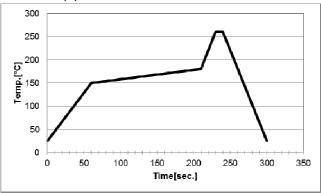
	Temp [°C]	Time[sec]
Preheating	+150 to +180	150 (typ.)
Peak	+260±5	10 (max.)
Total	—	300 (max.)

Frequency shift :  $\pm 2$ ppm

3.) Hand Soldering +350°C 3 sec MAX

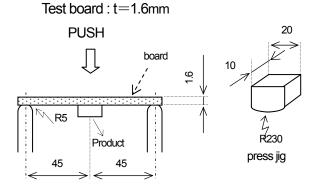
4.) Reflow Times 2 times

Reflow temp.profile



9.8 Intensity for bending in circuit board

Solder this product in center of the circuit board of  $40 \text{mm} \times 100 \text{mm}$ , and add the deflection of 3mm as the bottom figure.



UNIT : mm

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# 10. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

## (2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 5 times the ESR (Equivalent Series Resistance) of crystal unit.

# 11. Storage conditions

Please store product in below conditions, and use within 6 months. Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

# 12. Manufacturing location

Kyocera Crystal Device Corporation Plant Kyocera Crystal Device Corporation Shiga Yohkaichi Plant Kyocera Crystal Device (Thailand) Co., Ltd Kyocera Crystal Device Philippines, Inc.

## **13. Quality Assurance**

To be guaranteed by Kyocera Crystal Device Quality Assurance Division

## 14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1year of its delivery is waivered.

## 15. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.